



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC010N04LSC	Issued	17. February 2022
MA#	MA005620045		
Package	PG-TDSON-8-47	Weight*	104.42 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.517	1.45	1.45	14531	14531
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		122	
	non noble metal	zinc	7440-66-6	0.051	0.05		486	
	non noble metal	iron	7439-89-6	1.016	0.97		9729	
	non noble metal	copper	7440-50-8	41.248	39.51	40.54	395040	405377
wire	noble metal	gold	7440-57-5	0.046	0.04	0.04	436	436
encapsulation	organic material	carbon black	1333-86-4	0.122	0.12		1170	
	plastics	epoxy resin	-	4.763	4.56		45620	
	inorganic material	silicondioxide	60676-86-0	35.827	34.31	38.99	343126	389916
leadfinish	non noble metal	tin	7440-31-5	1.084	1.04	1.04	10380	10380
plating	noble metal	silver	7440-22-4	0.197	0.19	0.19	1883	1883
solder	non noble metal	tin	7440-31-5	0.042	0.04		403	
	noble metal	silver	7440-22-4	0.053	0.05		504	
	non noble metal	lead	7439-92-1	2.010	1.93	2.02	19255	20162
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			47	
	non noble metal	zinc	7440-66-6	0.020	0.02		189	
	non noble metal	iron	7439-89-6	0.394	0.38		3776	
	non noble metal	copper	7440-50-8	16.007	15.33	15.73	153303	157315
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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